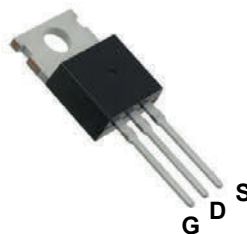
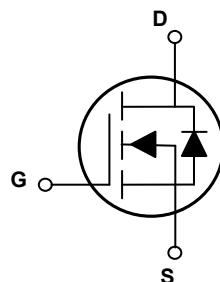


Main Product Characteristics

BV_{DSS}	600V
$R_{DS(ON)}$	99mΩ (Max)
I_D	36A



TO-220



Schematic Diagram



Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery

Description

The GSFT60R099 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies, EV Charger, motor driver and a wide variety of other applications.

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ¹ , $T_C=25^\circ\text{C}$	I_D	36	A
Continuous Drain Current ¹ , $T_C=100^\circ\text{C}$		22.8	
Pulsed Drain Current ² , $T_C=25^\circ\text{C}$	$I_{D,pulse}$	108	A
Continuous Diode Forward Current ¹ , $T_C=25^\circ\text{C}$	I_S	36	A
Diode Pulsed Current ² , $T_C=25^\circ\text{C}$	$I_{S,pulse}$	108	A
Power Dissipation ³ , $T_C=25^\circ\text{C}$	P_D	261	W
Single Pulsed Avalanche Energy ⁵	E_{AS}	845	mJ
MOSFET dv/dt Ruggedness, $V_{DS}=0$ to 480V	dv/dt	50	V/ns
Reverse Diode dv/dt, $V_{DS}=0$ to 480V, $I_{SD} \leq I_D$		50	
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.48	$^\circ\text{C/W}$
Thermal Resistance, Junction to Ambient ⁴	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Operation and Storage Temperature Range	T_{stg}, T_J	-55 to +150	$^\circ\text{C}$

Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =1mA	600	-	-	V
		V _{GS} =0V, I _D =1mA T _J =150°C	650	-	-	
Drain-Source Leakage Current	I _{DSS}	V _{DS} =600V, V _{GS} =0V	-	-	10	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±30V	-	-	±100	nA
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =18A	-	0.085	0.099	Ω
		V _{GS} =10V, I _D =18A T _J =150°C	-	0.195	-	
Gate Resistance	R _G	f=1MHz, Open drain	-	6.2	-	Ω
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =1mA	3.0	-	4.5	V
Dynamic and Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =400V, I _D =16A V _{GS} =10V	-	57.8	-	nC
Gate-Source Charge	Q _{gs}		-	17.2	-	
Gate-Drain Charge	Q _{gd}		-	18.8	-	
Gate Plateau Voltage	V _{plateau}		-	5.9	-	V
Turn-On Delay Time	t _{d(on)}	V _{DS} =400V, R _G =2.5Ω V _{GS} =10V, I _D =16A	-	40.2	-	nS
Rise Time	t _r		-	29.4	-	
Turn-Off Delay Time	t _{d(off)}		-	87.2	-	
Fall Time	t _f		-	8.4	-	
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V f=100KHz	-	3231	-	pF
Output Capacitance	C _{oss}		-	223.8	-	
Reverse Transfer Capacitance	C _{rss}		-	2.2	-	
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =36A	-	-	1.4	V
Reverse Recovery Time	t _{rr}	I _S =16A, di/dt=100A/μs	-	138	-	nS
Reverse Recovery Charge	Q _{rr}		-	756	-	nC
Peak Reverse Recovery Current	I _{rrm}		-	10.1	-	A

Note:

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. Pd is based on max. junction temperature, using junction-case thermal resistance.
4. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. copper, in a still air environment with T_A=25°C.
5. V_{DD}=100V, V_{GS}=10V, L=80mH, starting T_J=25°C.

Typical Electrical and Thermal Characteristic Curves

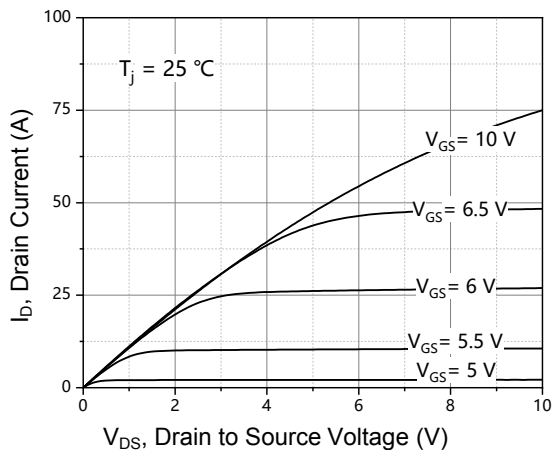


Figure 1. Typical Output Characteristics

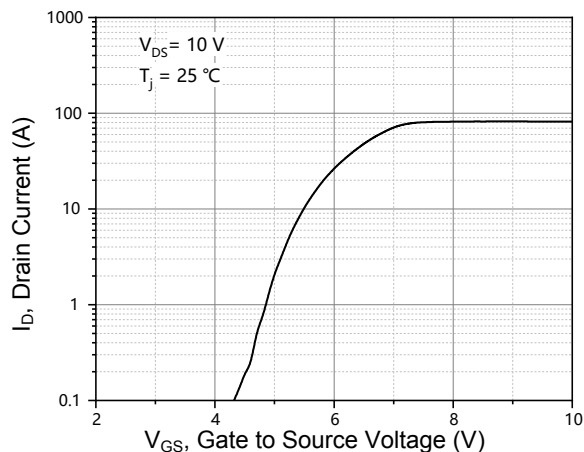


Figure 2. Transfer Characteristics

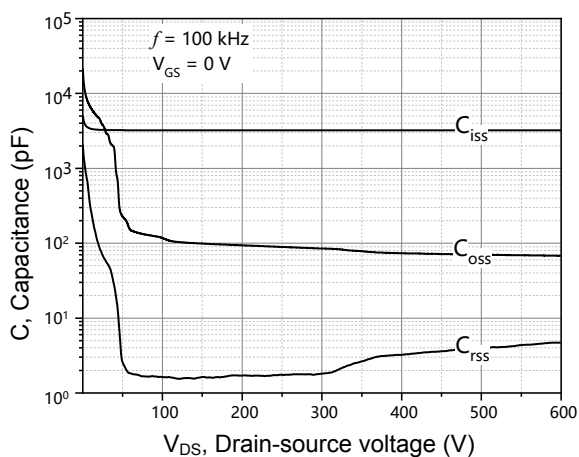


Figure 3. Typ. Capacitances

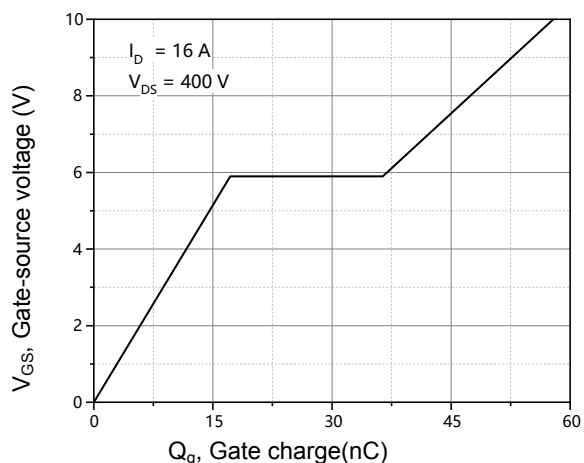


Figure 4. Typ. Gate Charge

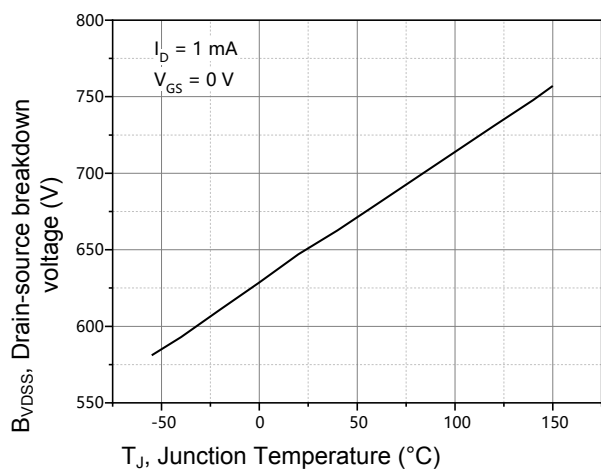


Figure 5. Drain-source breakdown voltage

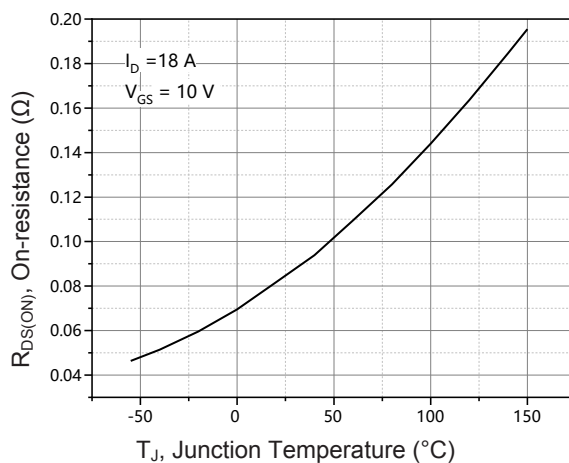


Figure 6. Drain-source on-state resistance

Typical Electrical and Thermal Characteristic Curves

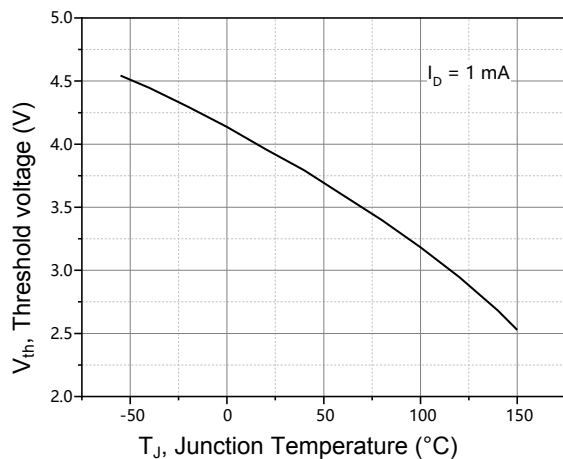


Figure 7. Threshold voltage

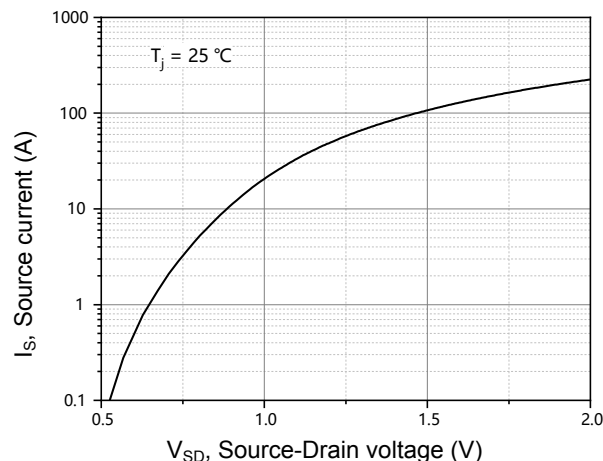


Figure 8. Forward characteristic of body diode

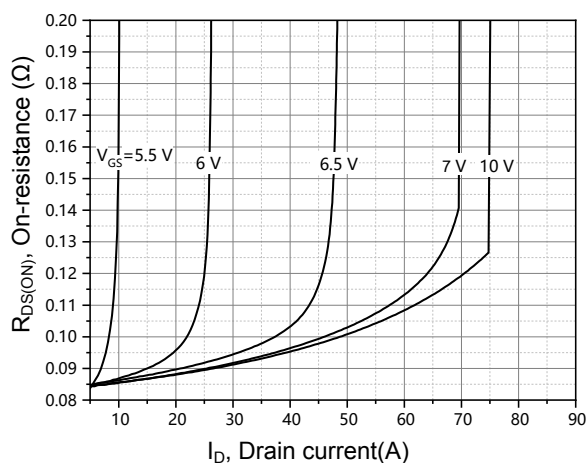


Figure 9. Drain-source on-state resistance

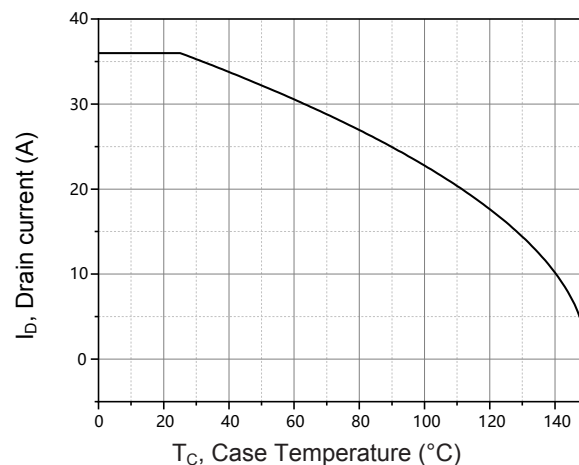


Figure 10. Drain current

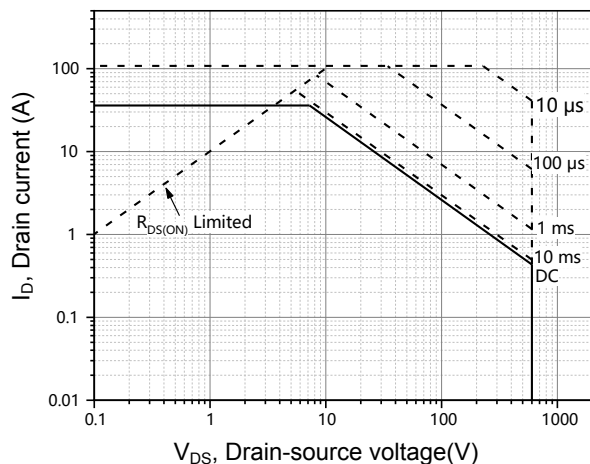


Figure 11. Safe operation area for $T_c=25^\circ\text{C}$

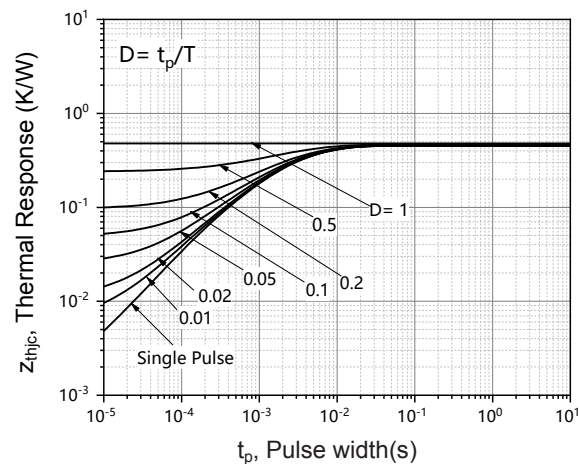
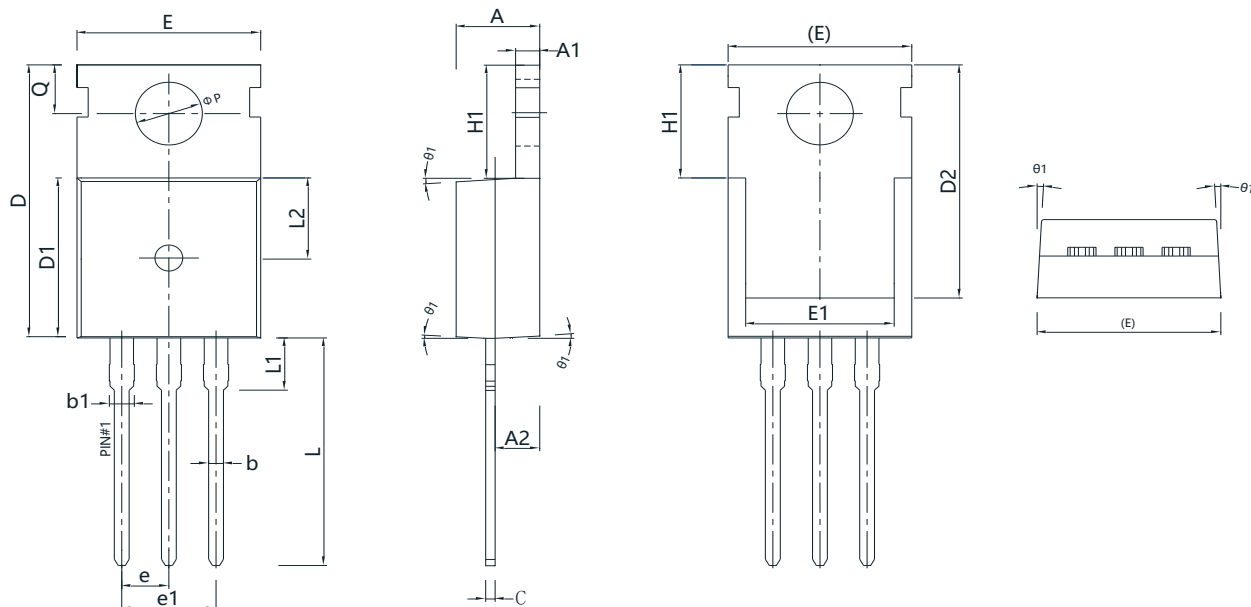


Figure 12. Max. transient thermal impedance

Package Outline Dimensions (TO-220)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.400	4.600	0.173	0.181
A1	1.270	1.330	0.050	0.052
A2	2.300	2.500	0.091	0.098
b	0.700	0.900	0.028	0.035
b1	1.270	1.400	0.050	0.055
c	0.450	0.600	0.018	0.024
D	15.300	16.100	0.602	0.634
D1	9.100	9.300	0.358	0.366
D2	13.100	13.700	0.516	0.539
E	9.700	10.200	0.382	0.402
E1	7.800	8.200	0.307	0.323
e	2.540 BSC		0.100 BSC	
e1	5.080 BSC		0.200 BSC	
H1	6.300	6.700	0.248	0.264
L	12.780	13.380	0.503	0.527
L1	-	3.500	-	0.138
L2	4.600 REF		0.181 REF	
ΦP	3.550	3.650	0.140	0.144
Q	2.730	2.870	0.107	0.113
θ1	1°	5°	1°	5°